

Product Specification

XBLW XBL1509

150KHz 3A PWM Buck DC/DC Converter

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Description

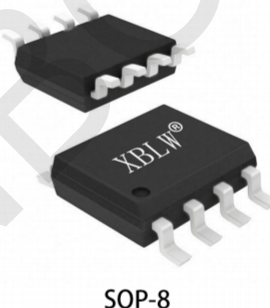
The XBL1509 is a monolithic IC designed for a step-down DC/DC converter, and own the ability of driving a 3A load without additional transistor. It saves board space. The external shutdown function can be controlled by logic level and then come into standby mode. The internal compensation makes feedback control having good line and load regulation without external design. Regarding protected function, thermal shutdown is to prevent over temperature operating from damage, and current limit is against over current operating of the output switch. If current limit function occurs and V_{FB} is down below 0.5V, the switching frequency will be reduced.

The XBL1509 operates at a switching frequency of 150KHz thus allow smaller sized filter components than what would be needed with lower frequency switching regulators. Other features include a guaranteed $\pm 4\%$ tolerance on output voltage under specified input voltage and output load conditions, and $\pm 15\%$ on the oscillator frequency.

The chips are available in a standard 8-lead SOP8 package.

Features

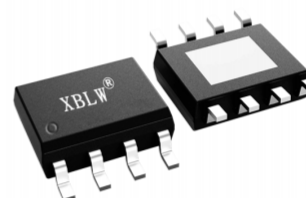
- 3.3V, 5V, 12V and Adjustable Output Version
- Output Adjustable Voltage From 1.23V to 37V
- Fixed 150KHz Switching Frequency
- Voltage Mode Non-synchronous PWM Control
- ON/OFF Shutdown Control Input
- Wide 4.5V to 40V Input Voltage Range
- Output Load Current: 3A
- Low Power Standby Mode
- Built-in Switching Transistor on Chip



SOP-8

Application

- Simple High-Efficiency Step-down Regulator
- On-card Switching Regulators
- Positive to Negative Converter

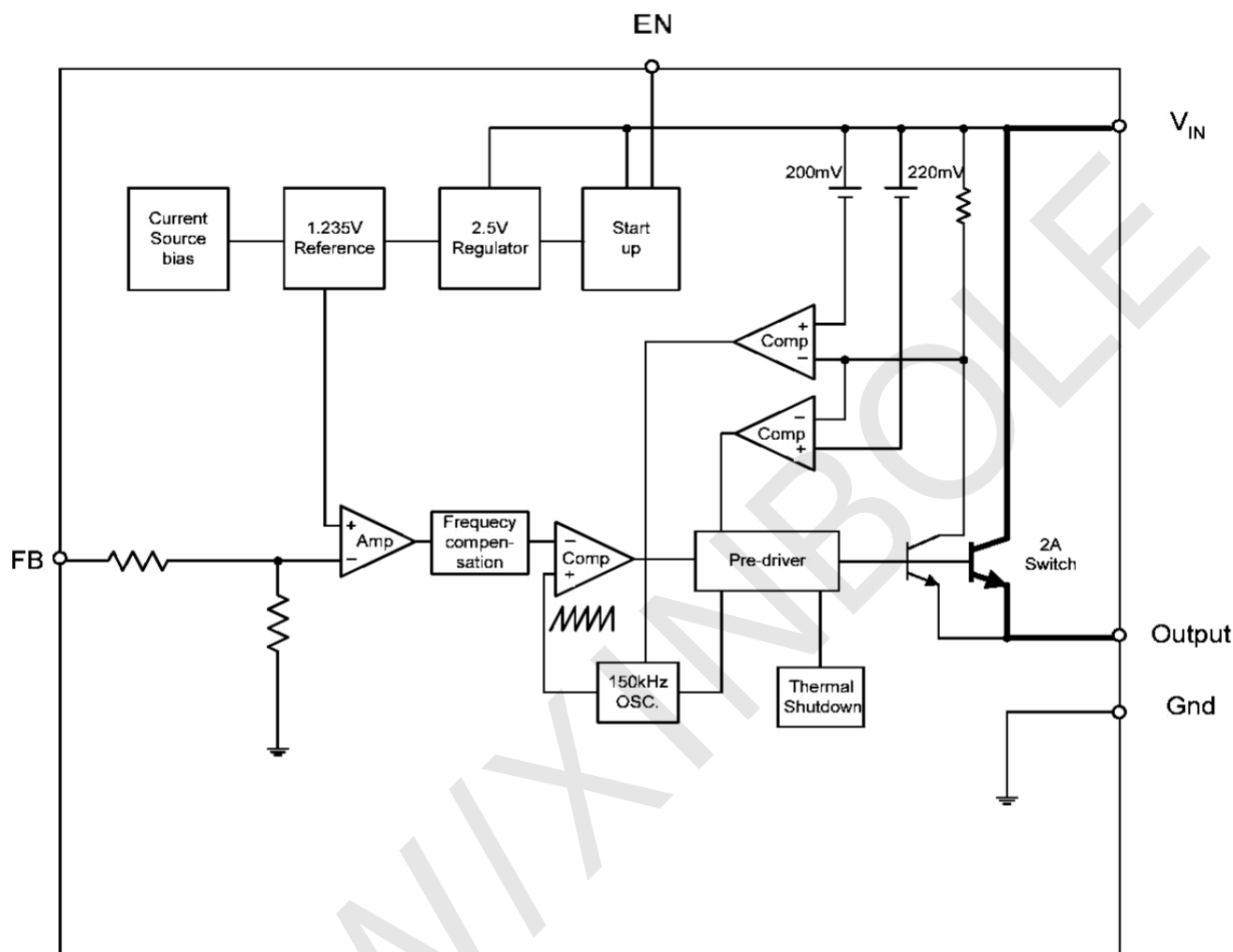


ESOP-8

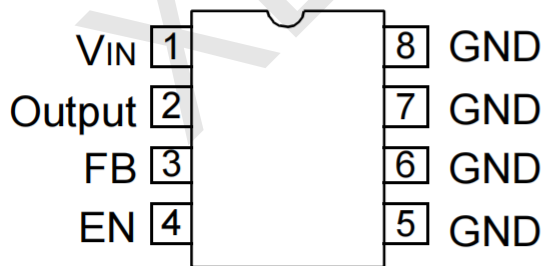
Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
XBLW XBL1509-3.3	SOP-8	1509-3.3	Tape	2500Pcs/Reel
XBLW XBL1509-5.0	SOP-8	1509-5.0	Tape	2500Pcs/Reel
XBLW XBL1509-12	SOP-8	1509-12	Tape	2500Pcs/Reel
XBLW XBL1509-ADJ	SOP-8	1509-ADJ	Tape	2500Pcs/Reel
XBLW XBL1509E-3.3	ESOP-8	1509E-3.3	Tape	2500Pcs/Reel
XBLW XBL1509E-5.0	ESOP-8	1509E-5.0	Tape	2500Pcs/Reel
XBLW XBL1509E-12	ESOP-8	1509E-12	Tape	2500Pcs/Reel
XBLW XBL1509E-ADJ	ESOP-8	1509E-ADJ	Tape	2500Pcs/Reel

Block Diagram



Pin Configuration



SOP-8/ESOP-8

Pin Descriptions

Name	Description
V _{IN}	Supply Voltage Input
Output	Power Switching Output
GND	Ground
FB	Output Voltage Feedback Control
EN	ON/OFF Shutdown

Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Supply Voltage	V_{IN}	+45	V
ON/OFF pin input voltage	V_{SD}	-0.3 ~ V_{IN}	V
Feedback pin voltage	V_{FB}	-0.3 ~ V_{IN}	V
Output voltage to ground	V_{OUT}	-1	V
Power dissipation	PD	Internally limited	W
Storage temperature	Tstg	-65 ~ +150	°C
Operating temperature	Topr	-40 ~ +125	°C
Operating voltage	V_{OP}	+4.5 ~ +40	V

Electrical Characteristics

(Refer to the test circuit, $V_{IN}=12V$ for 3.3V, 5V, adjustable version and $V_{IN}=24V$ for the 12V version, $I_{LOAD}=0.5A$)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Feedback Bias Current	I_{FB}	$V_{FB}=1.3V$ (Adjustable version only)		50	100	nA
Oscillator Frequency	Fosc		127	150	173	kHz
Saturation Voltage	V_{SAT}	$I_{OUT}=2A$, No outside circuit $V_{FB}=0V$ force driver on		1.2	1.5	V
Max. Duty Cycle(ON)	DC	$V_{FB}=0V$ force driver on	93	98		%
Min. Duty Cycle(OFF)		$V_{FB}=12V$ force driver off		0		
Current Limit	I_{CL}	Peak current, No outside circuit $V_{FB}=0V$ force driver on	3.0	4.0		A
Output Leakage Current (Output=0)	I_L	No outside circuit $V_{FB}=12V$ force driver off			2	mA
Output Leakage Current (Output=-1)		$V_{IN}=40V$		5	20	mA
Quiescent Current	I_Q	$V_{FB}=12V$ force driver off		5	10	mA
Standby Quiescent Current	I_{STBY}	ON/OFF pin=5V $V_{IN}=40V$		50	200	μA
ON/OFF pin Logic Input Threshold Voltage	V_{IL}	Low(regulator ON)			0.6	V
	V_{IH}	High(regulator OFF)	2.0			
ON/OFF pin Logic Input Current	I_H	$V_{LOGIC}=5.0V(OFF)$		12	30	μA
ON/OFF pin Input Current	I_L	$V_{LOGIC}=0.5V(ON)$		0	10	
Thermal Resistance	θ_{JC}	Junction to case		15		°C/W
Thermal Resistance with Copper Area of Approximately 3 in ²	θ_{JA}	Junction to ambient		70		°C/W

Electrical Characteristics

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
XBL1509-ADJ						
Output Feedback	V_{FB}	$4.5V \leq V_{IN} \leq 40V$ $0.2A \leq I_{LOAD} \leq 3A$ V_{OUT} programmed for 3V	1.193	1.230	1.267	V
Efficiency	η	$V_{IN} = 12V, I_{LOAD} = 3A$		74		%
XBL1509-3.3						
Output Voltage	V_{OUT}	$4.75V \leq V_{IN} \leq 40V$ $0.2A \leq I_{LOAD} \leq 3A$	3.168	3.300	3.432	V
Efficiency	η	$V_{IN} = 12V, I_{LOAD} = 3A$		76		%
XBL1509-5.0						
Output Voltage	V_{OUT}	$7V < V_{IN} < 40V$ $0.2A \leq I_{LOAD} \leq 3A$	4.80	5.00	5.20	V
Efficiency	η	$V_{IN} = 12V, I_{LOAD} = 3A$		83		%
XBL1509-12						
Output Voltage	V_{OUT}	$15V \leq V_{IN} \leq 40V$ $0.2A \leq I_{LOAD} \leq 3A$	11.52	12.00	12.48	V
Efficiency	η	$V_{IN} = 25V, I_{LOAD} = 3A$		90		%

Function Description

Pin Function +VIN

This is the positive input supply for the IC switching regulator. A suitable input bypass capacitor must be presented at this pin to minimize voltage transients and to supply the switching currents needed by the regulator.

Ground

Circuit ground.

Output

Internal switch. The voltage at this pin switches between $(+V_{IN} - V_{SAT})$ and approximately $-0.5V$, with a duty cycle of approximately V_{OUT} / V_{IN} . To minimize coupling to sensitive circuitry, the PC board copper area connected to this pin should be minimized.

Feedback

Senses the regulated output voltage to complete the feedback loop.

EN

Allows the switching regulator circuit to be shutdown using logic level signals thus dropping the total input supply current to approximately 150uA. Pulling this pin below a threshold voltage of approximately 1.3V turns the regulator on, and pulling this pin above 1.3V shuts the regulator down. If this shutdown feature is not needed, the EN pin can be wired to the ground pin.

Thermal Considerations

The SOP8 package needs a heat sink under most conditions. The size of the heatsink depends on the input voltage, the output voltage, the load current and the ambient temperature. The XBL1509 junction temperature rises above ambient temperature for a 3A load and different input and output voltages. The data for these curves was taken with the XBL1509 (SOP8 package) operating as a buck-switching regulator in an ambient temperature of 25°C (still air). These temperature increments are all approximate and are affected by many factors. Higher ambient temperatures require more heat sinker.

For the best thermal performance, wide copper traces and generous amounts of printed circuit board copper should be used in the board layout. (One exception is the output (switch) pin, which should not have large areas of copper.) Large areas of copper provide the best transfer of heat (lower thermal resistance) to the surrounding air, and moving air lowers the thermal resistance even further.

Package thermal resistance and junction temperature increments are all approximate. The increments are affected by a lot of factors. Some of these factors include board size, shape, thickness, position, location, and even board temperature. Other factors are, trace width, total printed circuit copper area, copper thickness, single or double-sided, multi-layer board and the amount of solder on the board.

The effectiveness of the PC board to dissipate heat also depends on the size, quantity and spacing of other components on the board, as well as whether the surrounding air is still or moving. Furthermore, some of these components such as the catch diode will add heat to the PC board and the heat can vary as the input voltage changes. For the inductor, depending on the physical size, type of core material and the DC resistance, it could either act as a heat sink taking heat away from the board, or it could add heat to the board.

Schottky Diode Selection Table

Current	Surface Mount	Through Hole	VR (The same as system maximum input voltage)				
			20V	30V	40V	50V	60V
1A		✓	1N5817	1N5818	1N5819		
		✓	1N5820	1N5821	1N5822		
2 and 3A		✓	MBR320	MBR330	MBR340	MBR350	MBR360
	✓		SK32	SK33	SK34	SK35	SK36
	✓			30WQ03	30WQ04	30WQ05	
		✓		31DQ03	31DQ04	31DQ05	
		✓	SR302	SR303	SR304	SR305	SR306

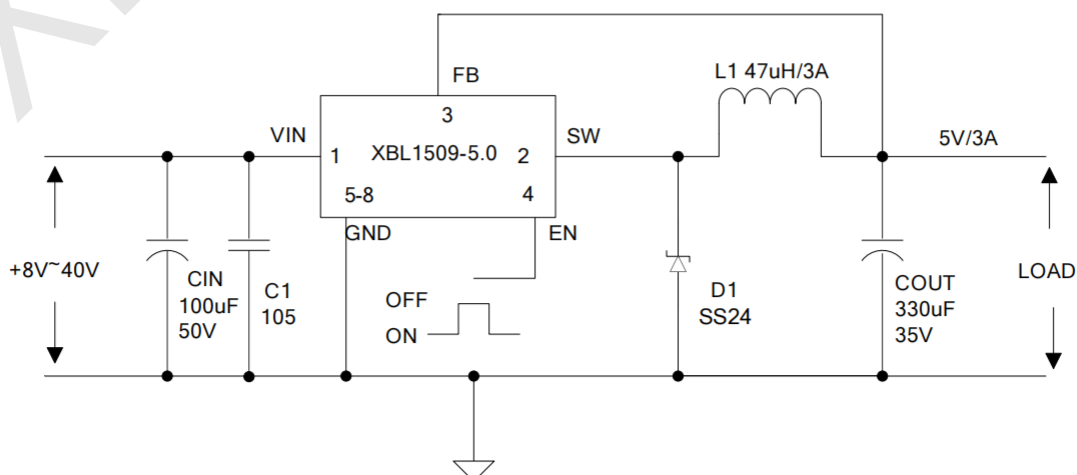
XBL1509 Series Buck Regulator Design Procedure (Adjustable Output)

Output Voltage (V)	Through Hole Output Electrolytic			Surface Mount Output Capacitor		
	Panasonic HFQ Series (uf/V)	Nichicon PL Series (uf/V)	Feedforward Capacitor	AVX TPS Series (uf/V)	Sprague 595D Series (uf/V)	Feedforward Capacitor
2	820/35	820/35	33nf	330/6.3	470/4	33nf
4	560/35	470/35	10nf	330/6.3	390/6.3	10nf
6	470/25	470/35	3.3nf	220/ 10	330/ 10	3.3nf
9	330/25	330/25	1.5nf	100/ 16	180/ 16	1.5nf
12	330/25	330/25	1nf	100/ 16	180/ 16	1nf
15	220/25	220/35	680pf	68/20	120/20	680pf
24	220/35	150/35	560pf	33/25	33/25	220pf
28	100/50	100/50	390pf	10/35	15/50	220pf

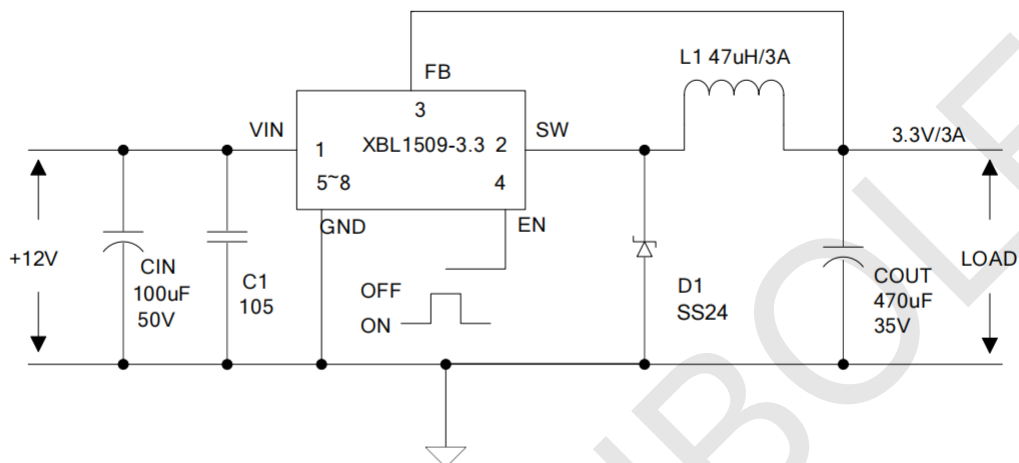
XBL1509 Series Buck Regulator Design Procedure (Fixed Output)

Conditions			Inductor (L1)	Output Capacitor (COUT)			
				Through Hole Electrolytic		Surface Mount Tantalum	
Output Voltage (V)	Load Current (A)	Max Input Voltage (V)	Inductance (uh)	Panasonic HFQ Series (uf/V)	Nichicon PL Series (uf/V)	AVX TPS Series (uf/V)	Sprague 595D Series (uf/V)
3.3	2 and 3	6	22	470/25	470/35	330/6.3	390/6.3
		10	33	330/35	330/35	330/6.3	390/6.3
		40	47	330/35	270/50	220/ 10	330/ 10
5	2 and 3	9	22	470/25	560/ 16	220/ 10	330/ 10
		20	68	180/35	180/35	100/ 10	270/ 10
		40	68	180/35	180/35	100/ 10	270/ 10
12	2 and 3	15	33	330/25	330/25	100/ 16	180/ 16
		20	68	180/25	180/25	100/ 16	120/20
		40	150	82/25	82/25	68/20	68/25

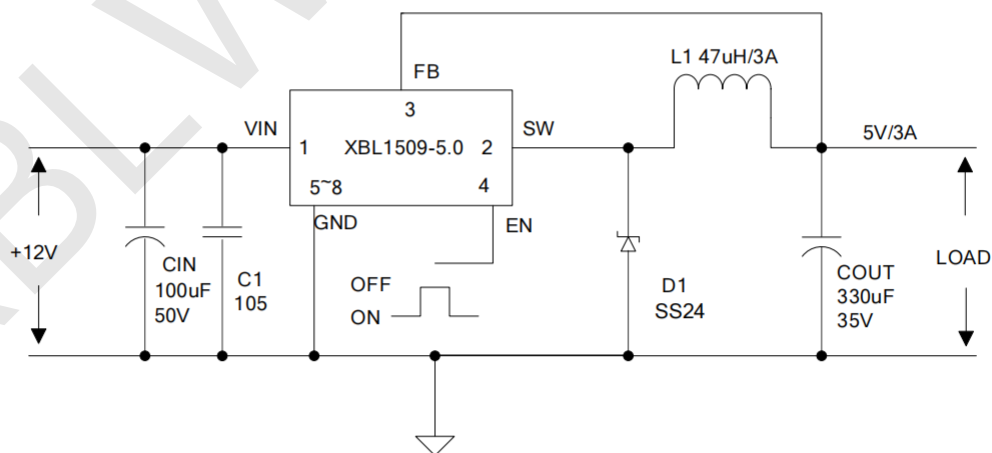
Typical Application Circuit



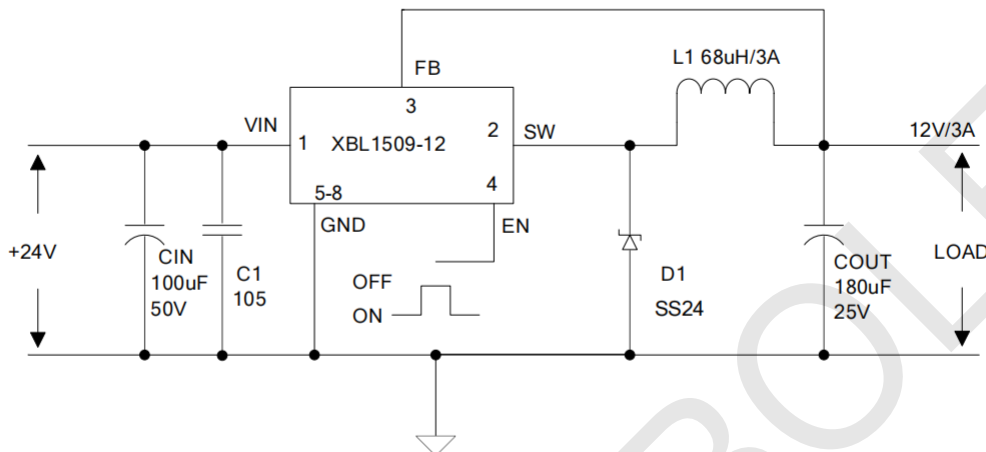
Typical System Application for 3.3V Version



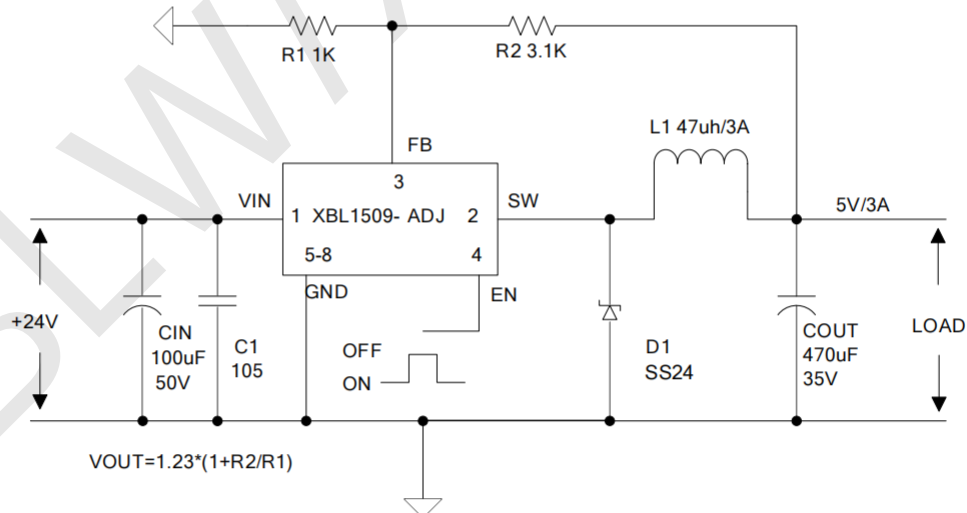
Typical System Application for 5V Version



Typical System Application for 12V Version

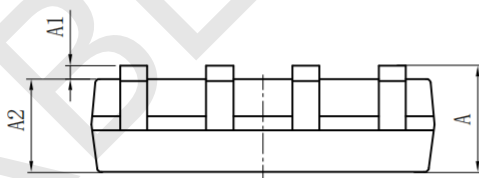
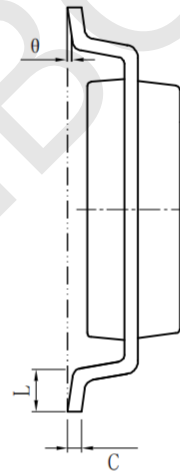
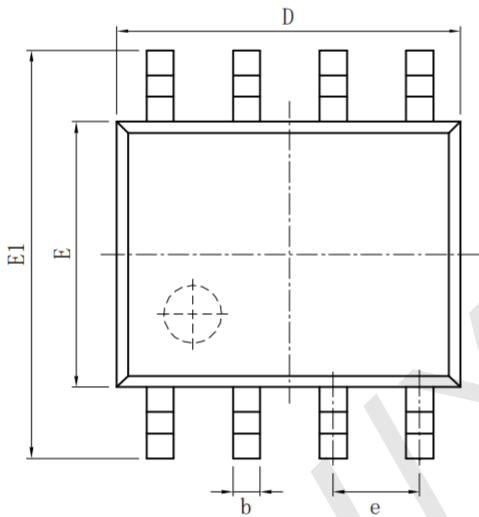


Typical System Application for ADJ Version



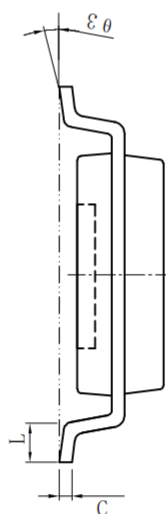
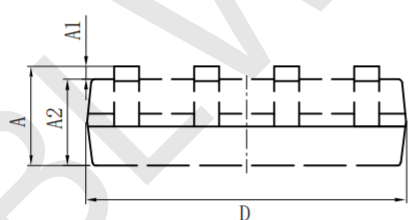
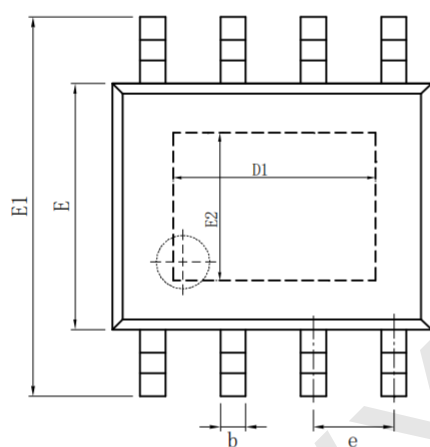
• SOP-8

Size Symbol	Dimensions In Millimeters		Size Symbol	Dimensions In Inches	
	Min(mm)	Max(mm)		Min(in)	Max(in)
A	1.350	1.750	A	0.053	0.069
A1	0.100	0.250	A1	0.004	0.010
A2	1.350	1.550	A2	0.053	0.061
b	0.330	0.510	b	0.013	0.020
c	0.170	0.250	c	0.006	0.010
D	4.700	5.100	D	0.185	0.200
E	3.800	4.000	E	0.150	0.157
E1	5.800	6.200	E1	0.228	0.224
e	1.270 (BSC)		e	0.050 (BSC)	
L	0.400	1.270	L	0.016	0.050
θ	0°	8°	θ	0°	8°



· ES0P-8

Symbol	Size	Dimensions In Millimeters		Symbol	Size	Dimensions In Inches	
		Min (mm)	Max (mm)			Min (in)	Max (in)
A		1.350	1.750	A		0.053	0.069
A1		0.050	0.150	A1		0.004	0.010
A2		1.350	1.550	A2		0.053	0.061
b		0.330	0.510	b		0.013	0.020
c		0.170	0.250	c		0.007	0.010
D		4.700	5.100	D		0.185	0.201
D1		3.202	3.402	D1		0.126	0.134
E		3.800	4.000	E		0.150	0.157
E1		5.800	6.200	E1		0.228	0.244
E2		2.313	2.513	E2		0.091	0.099
e		1.270 (BSC)		e		0.050 (BSC)	
L		0.400	1.270	L		0.016	0.050
θ		0°	8°	θ		0°	8°



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Specification information

Version	Release Date	New/Revised Content
V1.0	2023/10	Initial Writing
V2.0	2024/11	Update Template
V2.1	2026/04	Modify typical application diagram